# **OBIS CORE LS**

Next Generation Miniaturized OEM Laser Module

The Coherent OBIS CORE LS suite of products provide miniaturized building blocks for OEM instrument designers.

Consisting out of the Optically Pumped Semiconductor Laser (OPSL) technology core of OBIS LS laser with perfect beam parameters and proven reliability the CORE LS lasers are the low-risk choice for OEM instruments in life sciences applications.

If small laser foot print, low heat dissipation and perfect beam quality are required the OBIS CORE LS modules are the best fit for OEM i nstrument designers.

## **Features and Benefits**

- Miniaturized for Integration
- Compact and powerful
- Perfect beam quality
- Low heat dissipation
- Up to 200 mW of laser power

## Applications

- Confocal Microscopy
- DNA Sequencing
- Flow Cytometry
- Medical Imaging and Instrumentation
- Opthalmology





SPECIFICATIONS	OBIS CORE 488LS	OBIS CORE 505LS	OBIS CORE 514LS	OBIS CORE 532LS	
Wavelength <sup>1</sup> (nm)	488	505	514	532	
Output Power <sup>2</sup> (mW)	20, 60, 80, 100, 150, 200	30, 100, 150	20, 100, 150	20, 50, 80, 100, 150, 200	
Spatial Mode	TEM00	TEM00	TEM <sub>00</sub>	TEM00	
M² (Beam Quality)	≤1.1	≤1.1	≤1.1	≤1.1	
Beam Asymmetry	≤1:1.1	≤1:1.1	≤1:1.1	≤1:1.1	
Beam Diameter at 1/e² (mm)	0.7 ±0.05	0.7 ±0.05	0.7 ±0.05	0.7 ±0.05	
Beam Divergence (mrad, full-angle)	<1.2	<1.2	<1.2	<1.2	
Pointing Stability (µrad) (over 2 hours after warm-up and ±3°C)	<30	<30	<30	<30	
Pointing Stability Over Temperature (µrad/°C)	<5	<5	<5	<5	
RMS Noise (%) (20 Hz to 20 MHz)	≤0.25	≤0.25	≤0.25	≤0.25	
Peak-to-Peak Noise (%) (20 Hz to 20 kHz)	<1	<1	<1	<1	
Long-Term Power Stability (%) (8 hours, ±3°C)	<2	<2	<2	<2	
Warm-Up Time <sup>3</sup> (minutes) (from cold start)	<5	<5	<5	<5	
Polarization Ratio	Minimum 100:1, Vertical ±5°	Minimum 100:1, Vertical ±5°	Minimum 100:1, Vertical ±5°	Minimum 100:1, Vertical ±5°	
Laser Drive Modes	CW, Analog Modulation, Digital Modulation, Computer Control				
Digital Modulation Maximum Bandwidth (kHz) Rise Time (10% to 90%) (ms) Fall Time (10% to 90%) (µs) Extinction Ratio	1 <1 <100 on/no emission	1 <1 <100 on/no emission	1 <1 <100 on/no emission	1 <1 <100 on/no emission	
Analog Modulation Maximum Bandwidth (kHz) Rise Time (10% to 90%) (ms) Fall Time (10% to 90%) (μs)	1 <1 <1	1 <1 <1	1 <1 <1	1 <1 <1	
Dynamic Power Range (%)	20 to 110	20 to 110	20 to 110	20 to 110	
Static Alignment Tolerances Beam Position from Reference <sup>4</sup> (mm) Beam Angle <sup>4</sup> (mrad) Beam Waist Position at Exit Window (mm)	<0.5 <2.5 ±215	<0.5 <2.5 ±215	<0.5 <2.5 ±215	<0.5 <2.5 ±215	
Laser Safety Classification	Зb	3b	3b	Зb	
Power Consumption (W)	Typical 5 to 8, Max. 12	Typical 5 to 8, Max. 12	Typical 5 to 8, Max. 12	Typical 5 to 8, Max. 12	
Laser Head Baseplate Temp. (Max., °C)	40	40	40	40	
CORE LS Controller Baseplate Temp. (Max., °C)	55	55	55	55	
Heat Dissipation of Laser Head <sup>5</sup> (W)	Typical 2 to 4, Max. 5	Typical 2 to 4, Max. 5	Typical 2 to 4, Max. 5	Typical 2 to 4, Max. 5	
Heat Dissipation of CORE LS Controller <sup>5</sup> (W)	Typical 3 to 5, Max. 6	Typical 3 to 5, Max. 6	Typical 3 to 5, Max. 6	Typical 3 to 5, Max. 6	
Ambient Temperature <sup>6</sup> Operating Condition <sup>7</sup> (°C) Non-Operating Condition (°C)	15 to 40 -20 to +60	15 to 40 -20 to +60	15 to 40 -20 to +60	15 to 40 -20 to +60	
Shock Tolerance (g) (6 ms)	30	30	30	30	

Laser-to-laser tolerance. All CORE LS versions ±2 nm.
Residual laser emission at 808 nm fundamental within beam at 100 mm distance <0.1 mW.
For LS versions typical power-on delay 3 minute.
See mechanical drawing for exit beam location.
Heat load depends on laser power level. Heat dissipation throught baseplate of laser head or controller.
Non-Condensing.
CORE LS laser head baseplate temperature needs to be maintained at ≤40°C



PECIFICATIONS	OBIS CORE 552LS	OBIS CORE 561LS	OBIS CORE 594LS
Wavelength <sup>1</sup> (nm)	552	561	594
Dutput Power <sup>2</sup> (mW)	20, 60, 80, 100, 150	20, 50, 80, 100, 150, 200	20, 60, 100
Spatial Mode	TEM <sub>00</sub>	TEM <sub>00</sub>	TEM <sub>00</sub>
M² (Beam Quality)	≤1.1	≤1.1	≤1.1
Beam Asymmetry	≤1:1.1	≤1:1.1	≤1:1.1
Beam Diameter at 1/e² (mm)	0.7 ±0.05	0.7 ±0.05	0.7 ±0.05
Beam Divergence (mrad, full-angle)	<1.2	<1.2	<1.2
Pointing Stability (µrad) over 2 hours after warm-up and ±3°C)	<30	<30	<30
Pointing Stability Over Temperature (µrad/°C)	<5	<5	<5
RMS Noise (%) (20 Hz to 20 MHz)	≤0.25	≤0.25	≤0.25
Peak-to-Peak Noise (%) (20 Hz to 20 kHz)	<1	<1	<1
Long-Term Power Stability (%) (8 hours, ±3°C)	<2	<2	<2
Warm-Up Time <sup>3</sup> (minutes) (from cold start)	<5	<5	<5
Polarization Ratio	Minimum 100:1, Vertical ±5°	Minimum 100:1, Vertical ±5°	Minimum 100:1, Vertical ±5°
aser Drive Modes	CW, Analog N	Iodulation, Digital Modulation, Com	nputer Control
Digital Modulation Maximum Bandwidth (kHz) Rise Time (10% to 90%) (ms) Fall Time (10% to 90%) (µs) Extinction Ratio	1 <1 <100 on/no emission	1 <1 <100 on/no emission	1 <1 <100 on/no emission
Analog Modulation Maximum Bandwidth (kHz) Rise Time (10% to 90%) (ms) Fall Time (10% to 90%) (μs) Dynamic Power Range (%)	1 <1 <1 20 to 110	1 <1 <1 20 to 110	1 <1 <1 20 to 110
Static Alignment Tolerances Beam Position from Reference <sup>4</sup> (mm) Beam Angle <sup>4</sup> (mrad) Beam Waist Position at Exit Window (mm)	<0.5 <2.5 ±215	<0.5 <2.5 ±215	<0.5 <2.5 ±215
Laser Safety Classification	3b	3b	Зb
Power Consumption (W)	Typical 5 to 8, Max. 12	Typical 5 to 8, Max. 12	Typical 5 to 8, Max. 12
aser Head Baseplate Temp. (Max., °C)	40	40	40
CORE LS Controller Baseplate Temp. (Max., °C)	55	55	55
leat Dissipation of Laser Head <sup>5</sup> (W)	Typical 2 to 4, Max. 5	Typical 2 to 4, Max. 5	Typical 2 to 4, Max. 5
leat Dissipation of CORE LS Controller <sup>5</sup> (W)	Typical 3 to 5, Max. 6	Typical 3 to 5, Max. 6	Typical 3 to 5, Max. 6
Ambient Temperature <sup>6</sup> Operating Condition <sup>7</sup> (°C) Non-Operating Condition (°C)	15 to 40 -20 to +60	15 to 40 -20 to +60	15 to 40 -20 to +60
Shock Tolerance (g) (6 ms)	30	30	30

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Residual laser emission at 808 nm fundamental within beam at 100 mm distance <0.1 mW.
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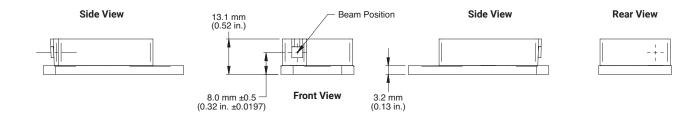
6 Non-Condensing.
7 CORE LS laser head baseplate temperature needs to be maintained at ≤40°C

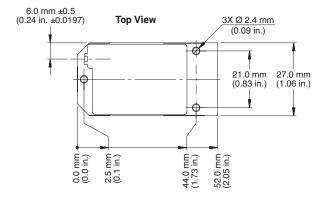


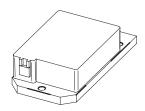
UTILITY AND ENVIRONMENTAL REQUIREMENTS			
Operating Voltage <sup>1</sup> (VDC)	12 ±2		
Dimensions (L x W x H) Laser Head (mm) CORE LS Controller Kit (mm)	52 x 27 x 13 mm (2.05 x 1.06 x 0.51 in.) 115 x 33 x 16 mm (4.53 x 1.30 x 0.63 in.)		
Cable, Laser Head to Controller (mm) (3 different lengths available) Weights	150, 300, 500 mm (5.91, 11.81, 19.69 in.)		
Laser Head CORE LS Controller Kit	22 g (0.05 lbs.) 81 g (0.18 lbs.)		

### MECHANICAL SPECIFICATIONS

#### **OBIS CORE LS**



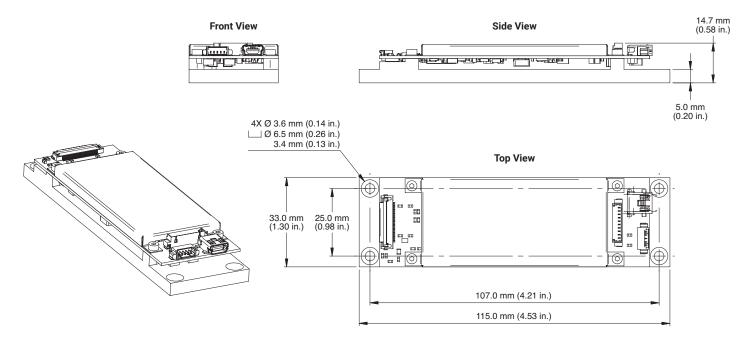






## **MECHANICAL SPECIFICATIONS**

#### **OBIS CORE LS Controller**





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Coherent follows a policy of continuous product improvement. Specifications are subject to change without notice.

Coherent offers a limited warranty for all OBIS CORE LS Lasers. For full details of this warranty coverage, please refer to the Service section at www.coherent.com or contact your local Sales or Service Representative.

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